

Fig. 1

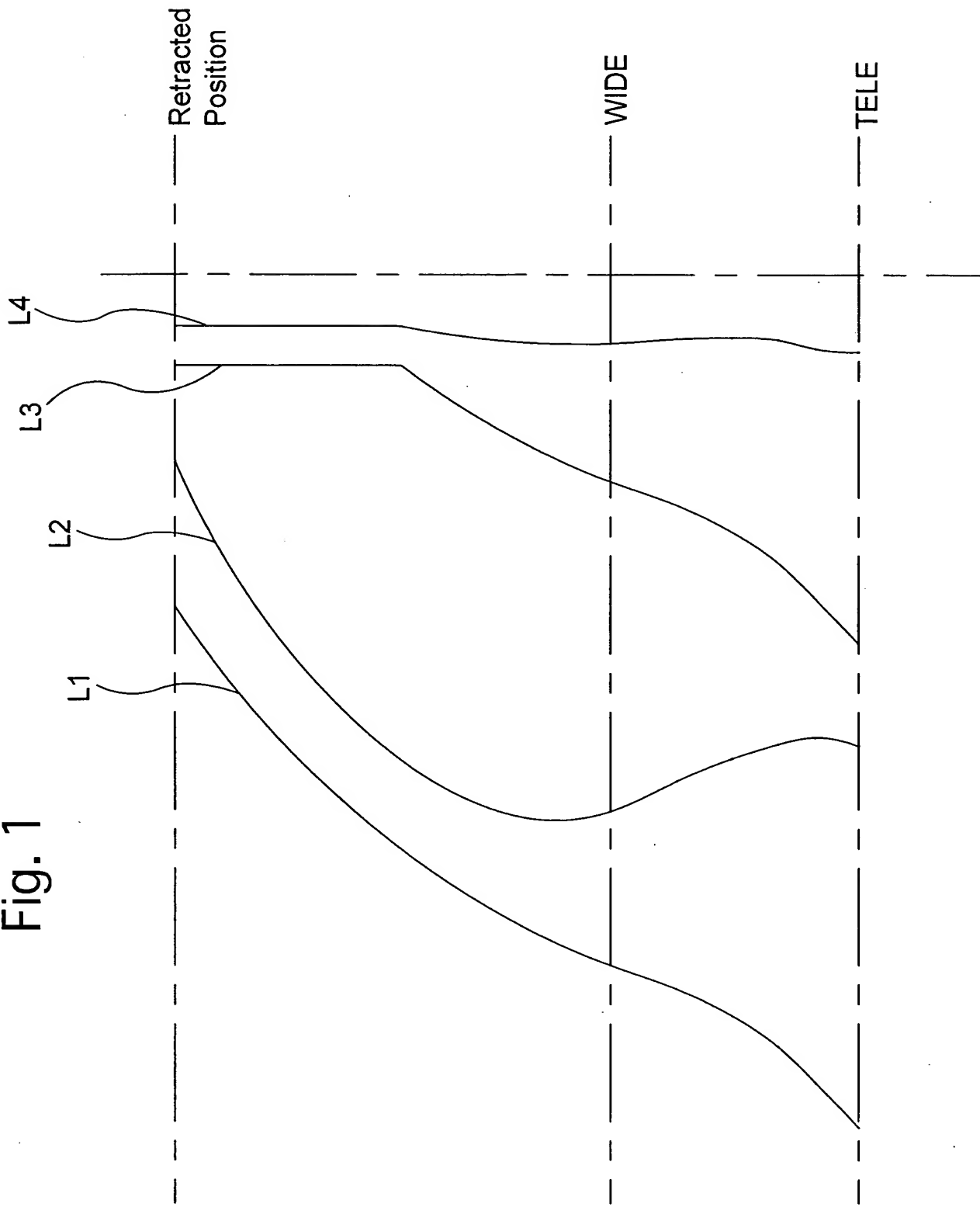


Fig. 2

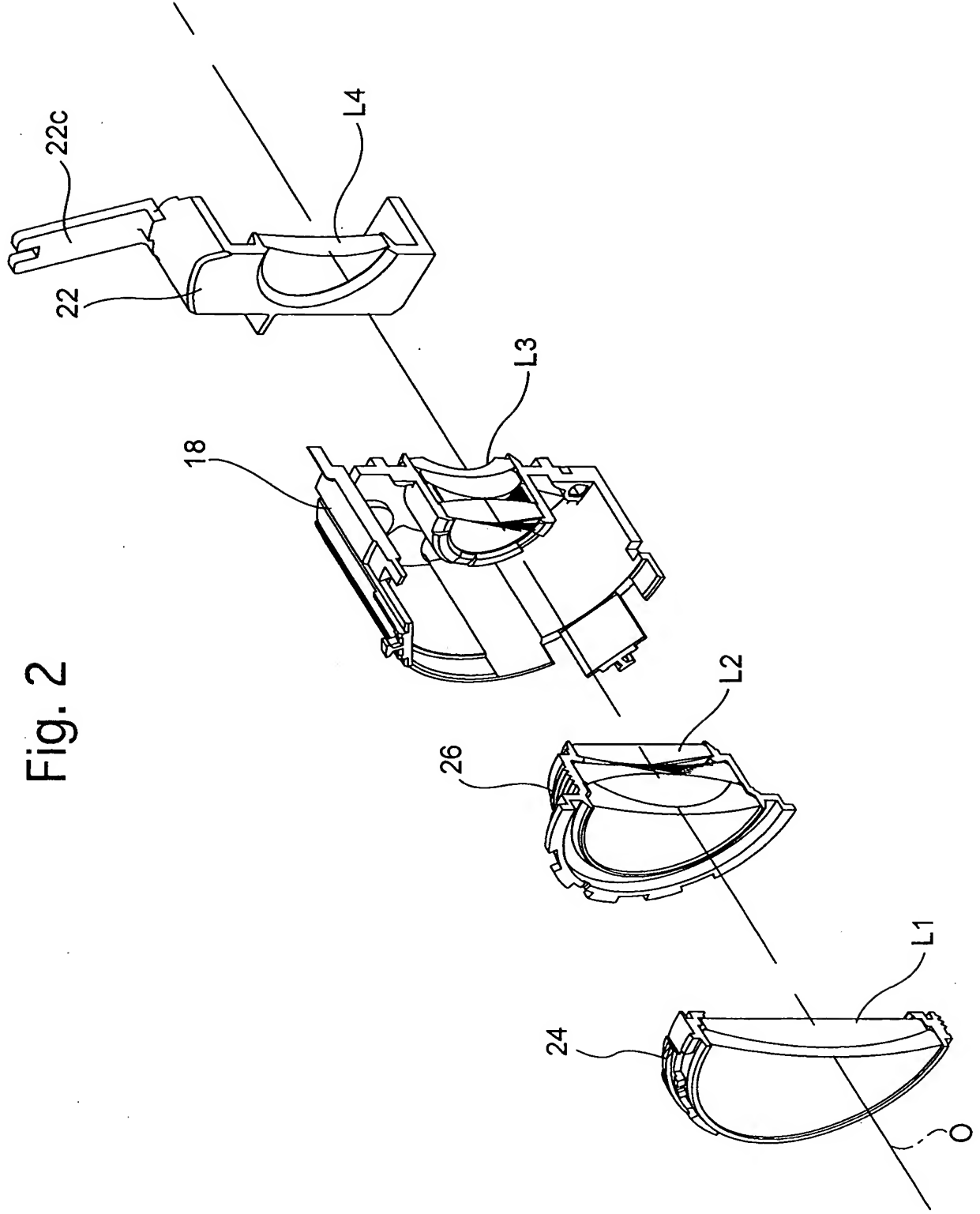


Fig. 3

Fig. 3 is a detailed cross-sectional view of a multi-layered electronic device assembly. The assembly consists of a base substrate 10 with multiple layers 11, 12, 13, 14, 15(15X), 16, 17, and 18. A central core 19 is surrounded by a conductive layer 20. The assembly is divided into four vertical sections labeled L1, L2, L3, and L4. Section L1 contains a component 21. Section L2 contains a component 22. Section L3 contains a component 23. Section L4 contains a component 24. A central vertical channel 25 is shown. Various other components are labeled with numbers 1 through 25. Section lines VI-VI and VII-VII are indicated.

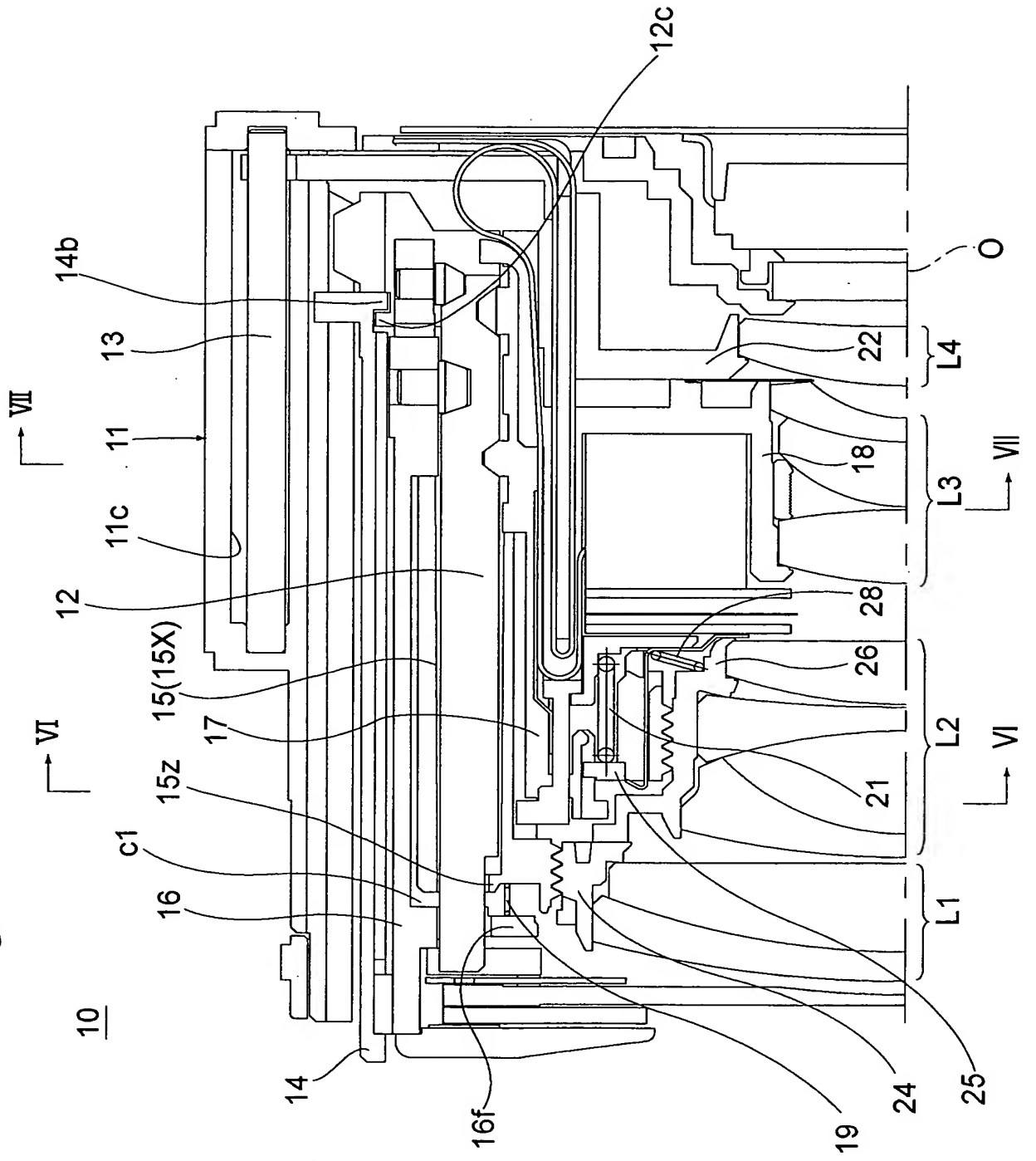


Fig. 4

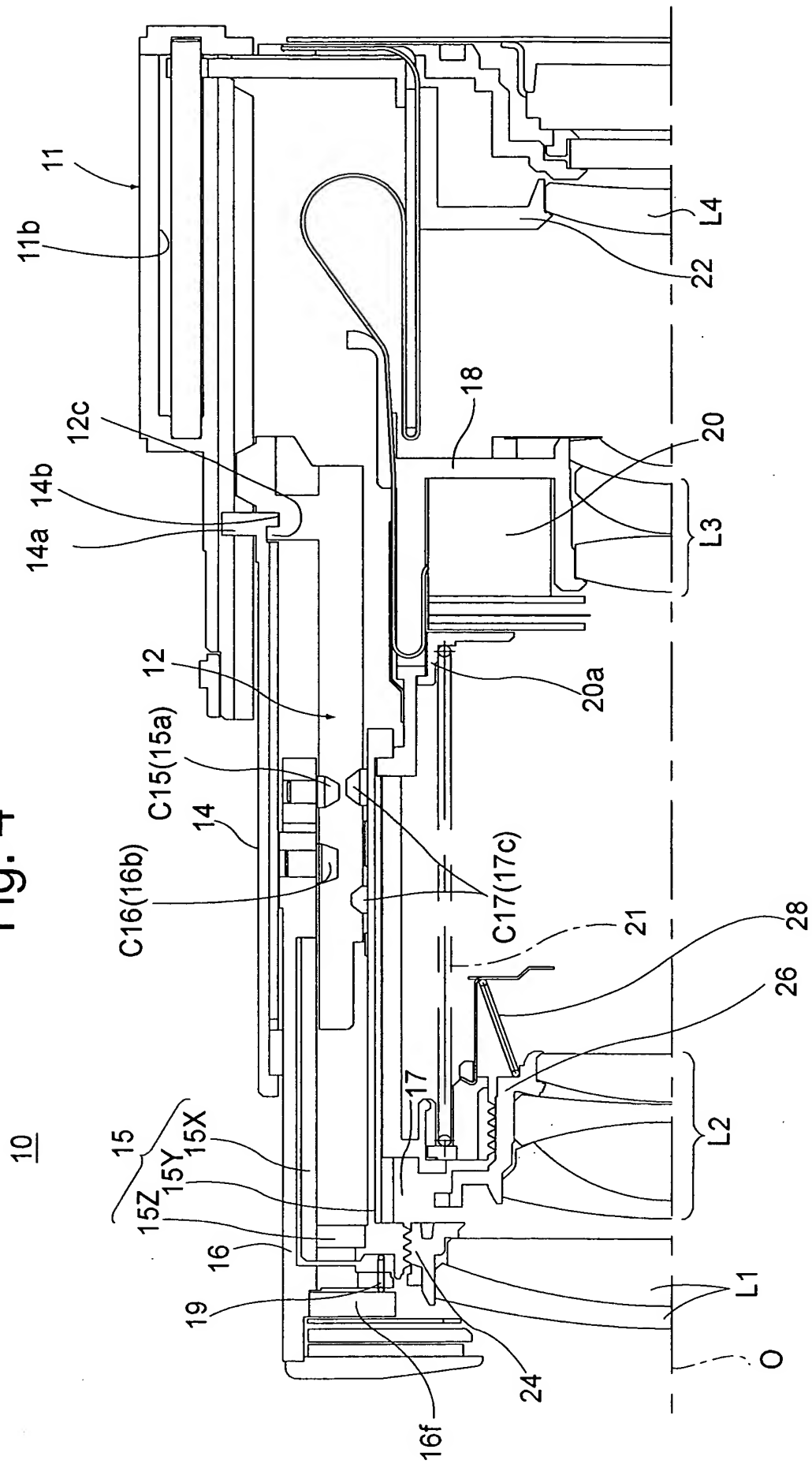


Fig. 5

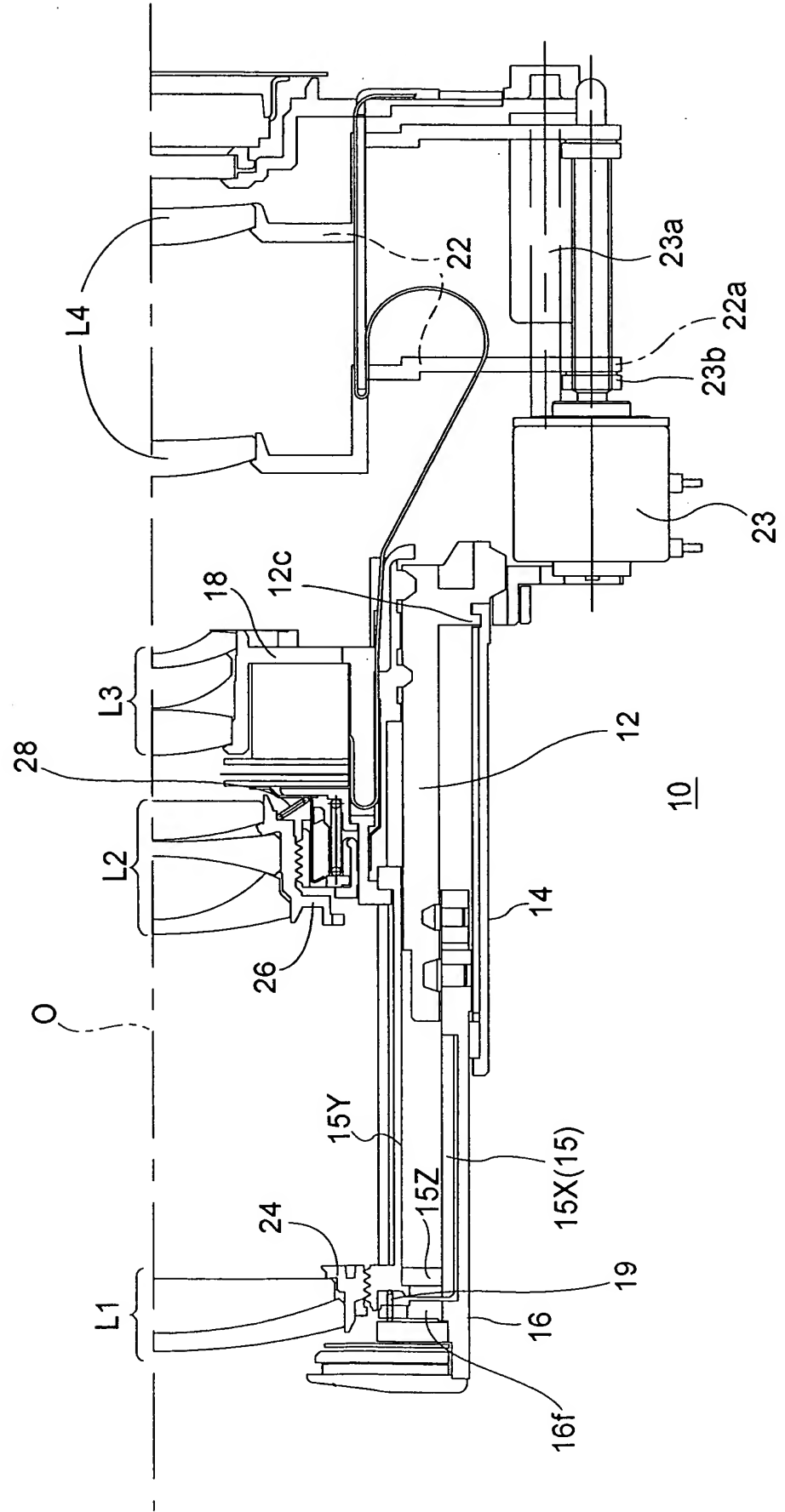


Fig. 6

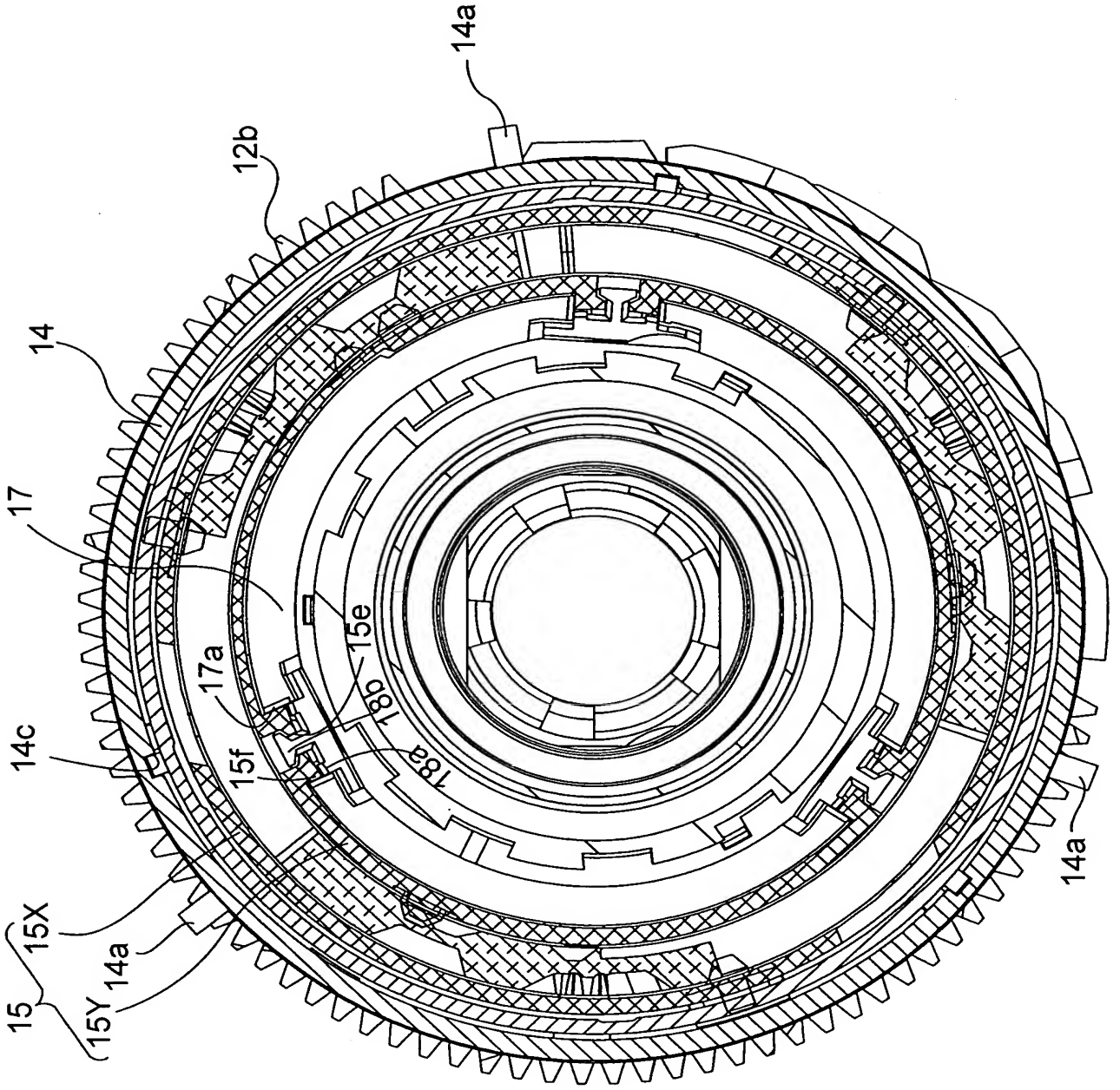


Fig. 7

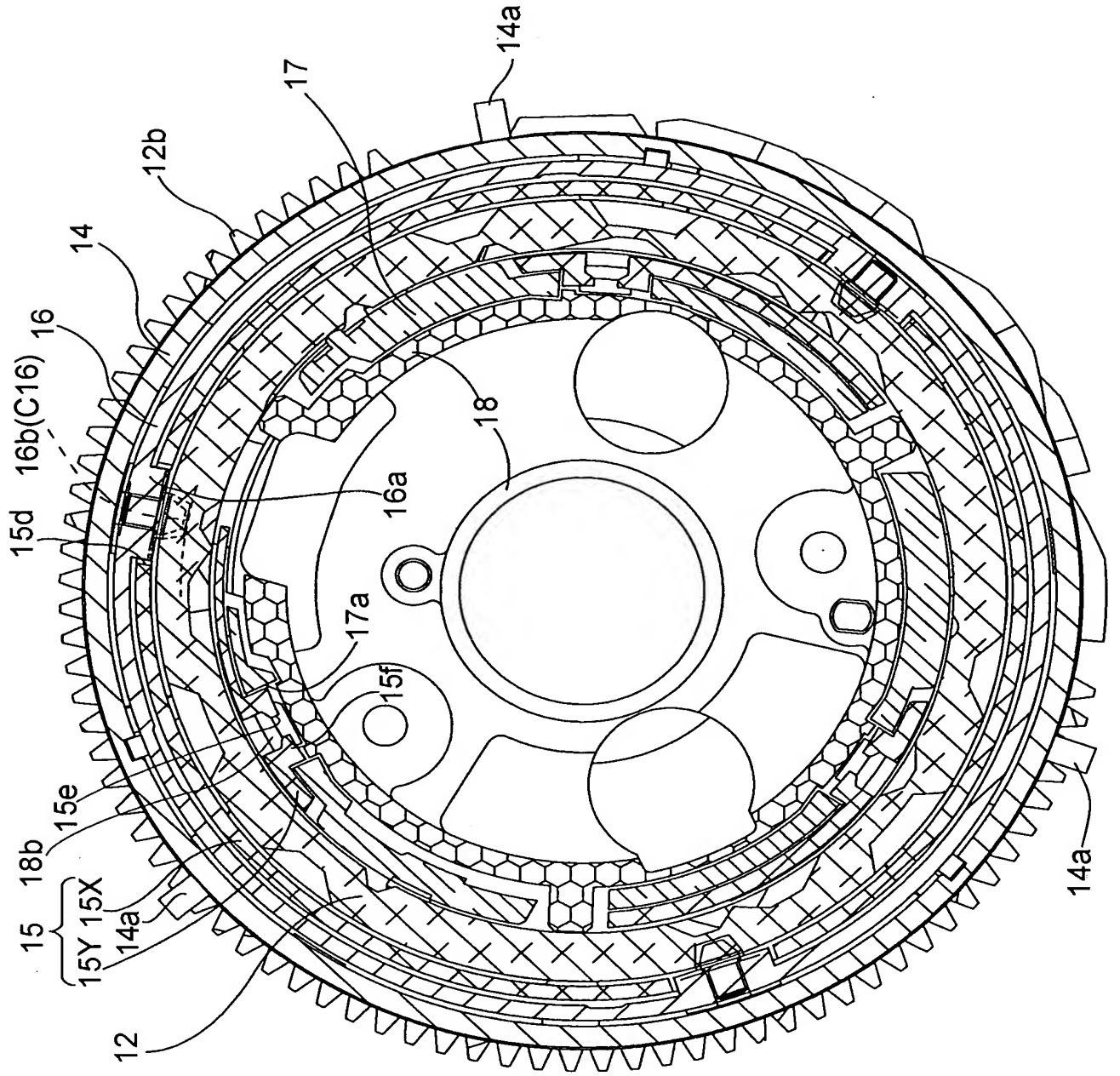


Fig. 8

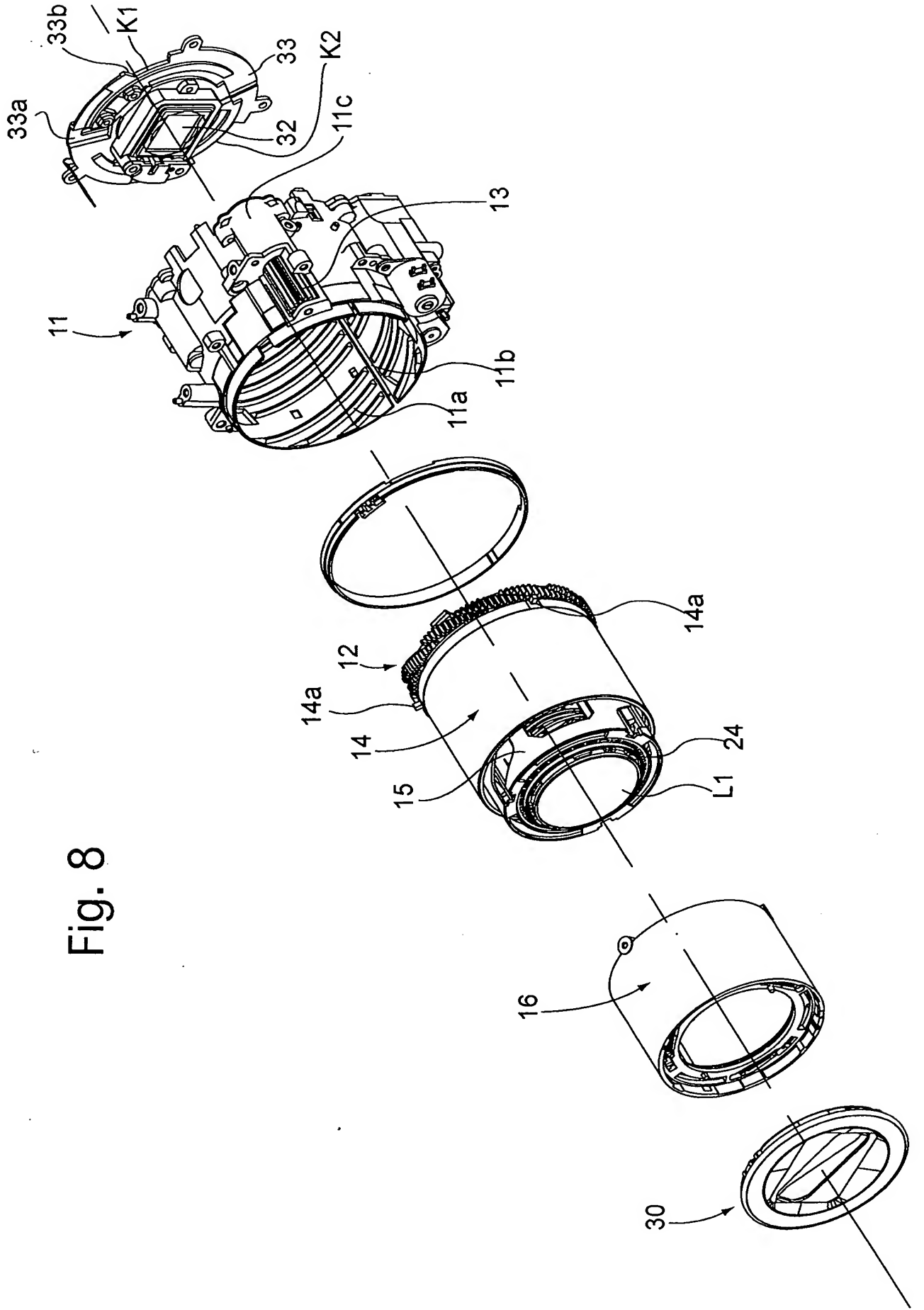
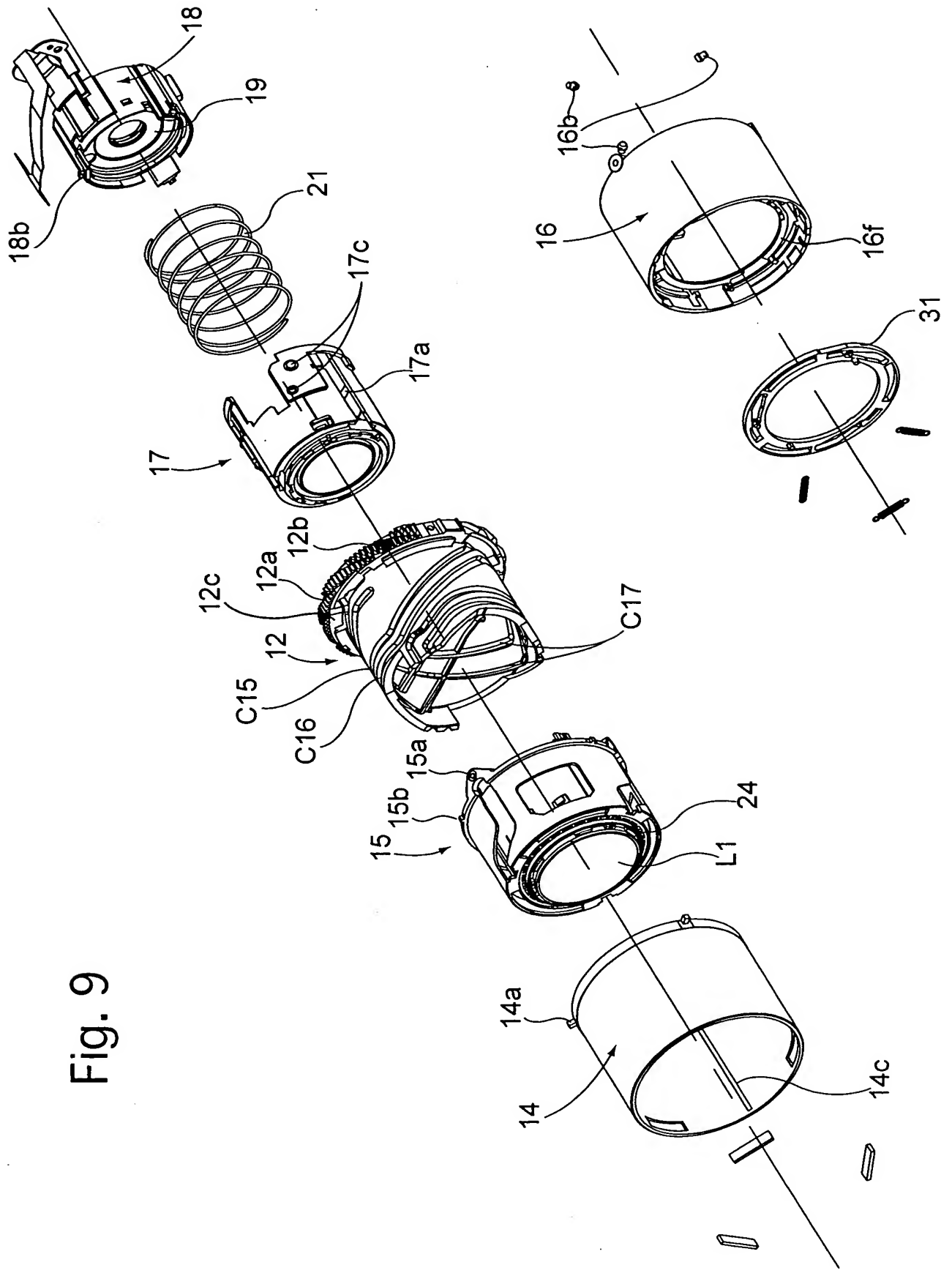


Fig. 9



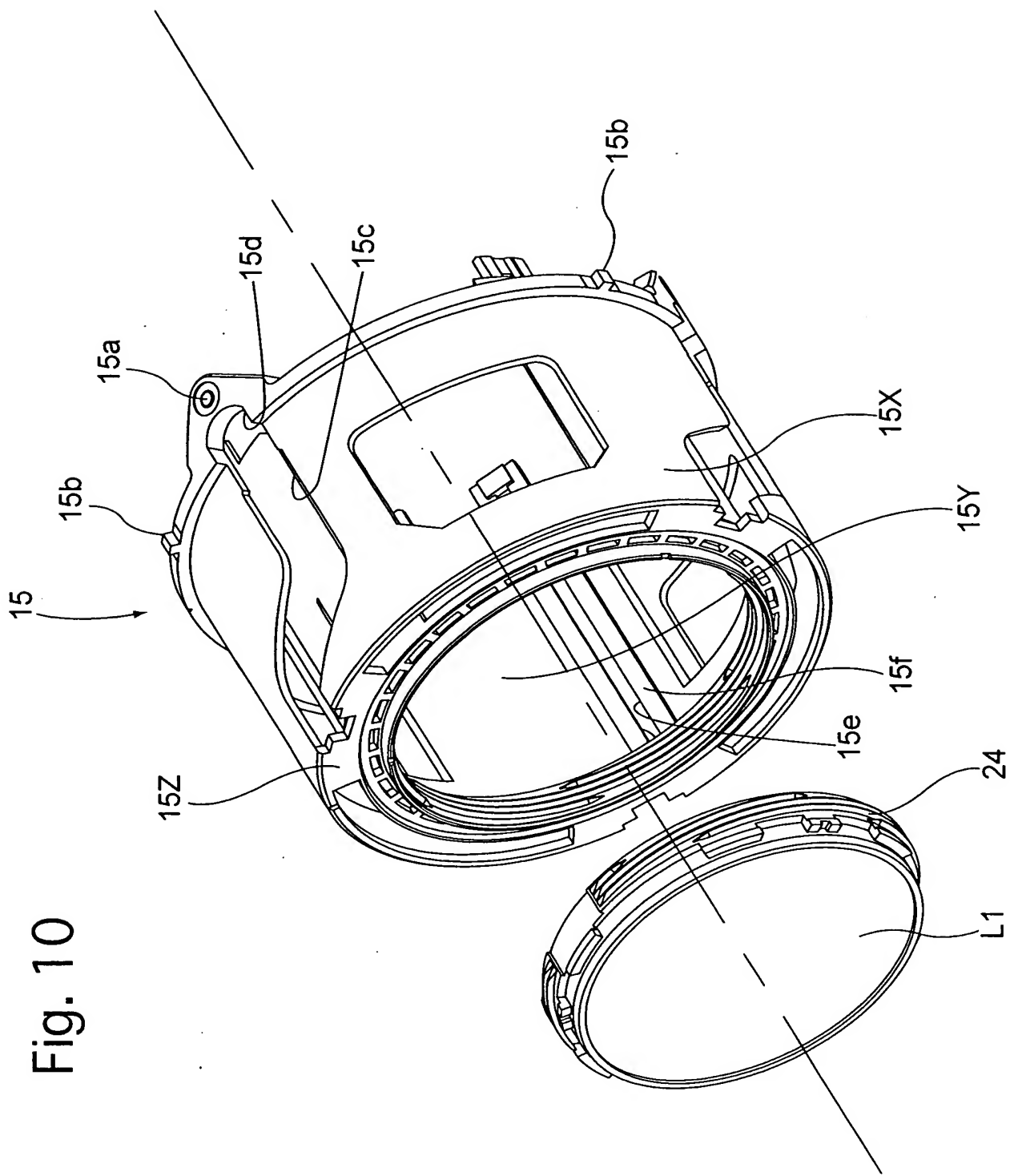


Fig. 10

Fig. 11

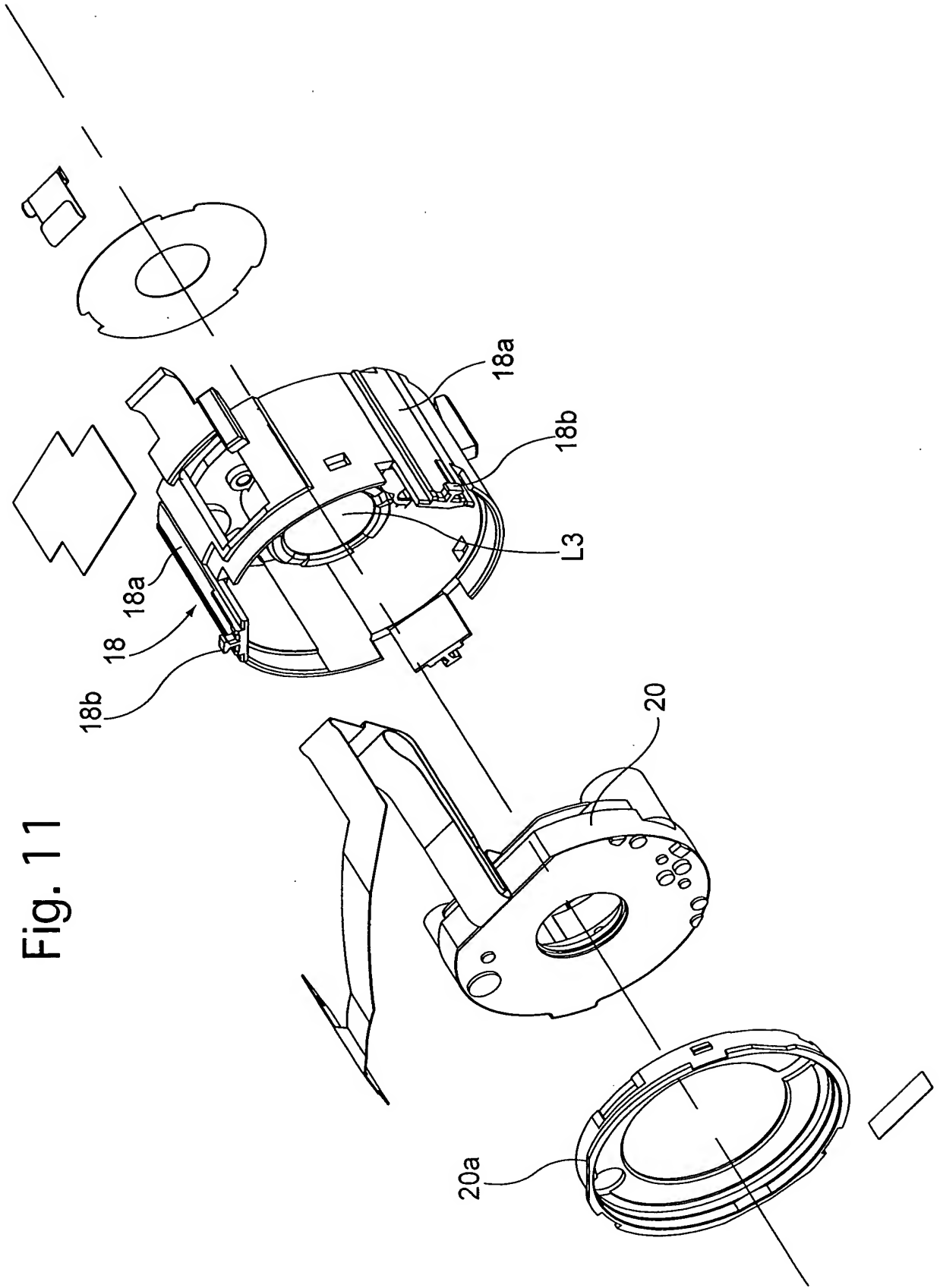


Fig. 12

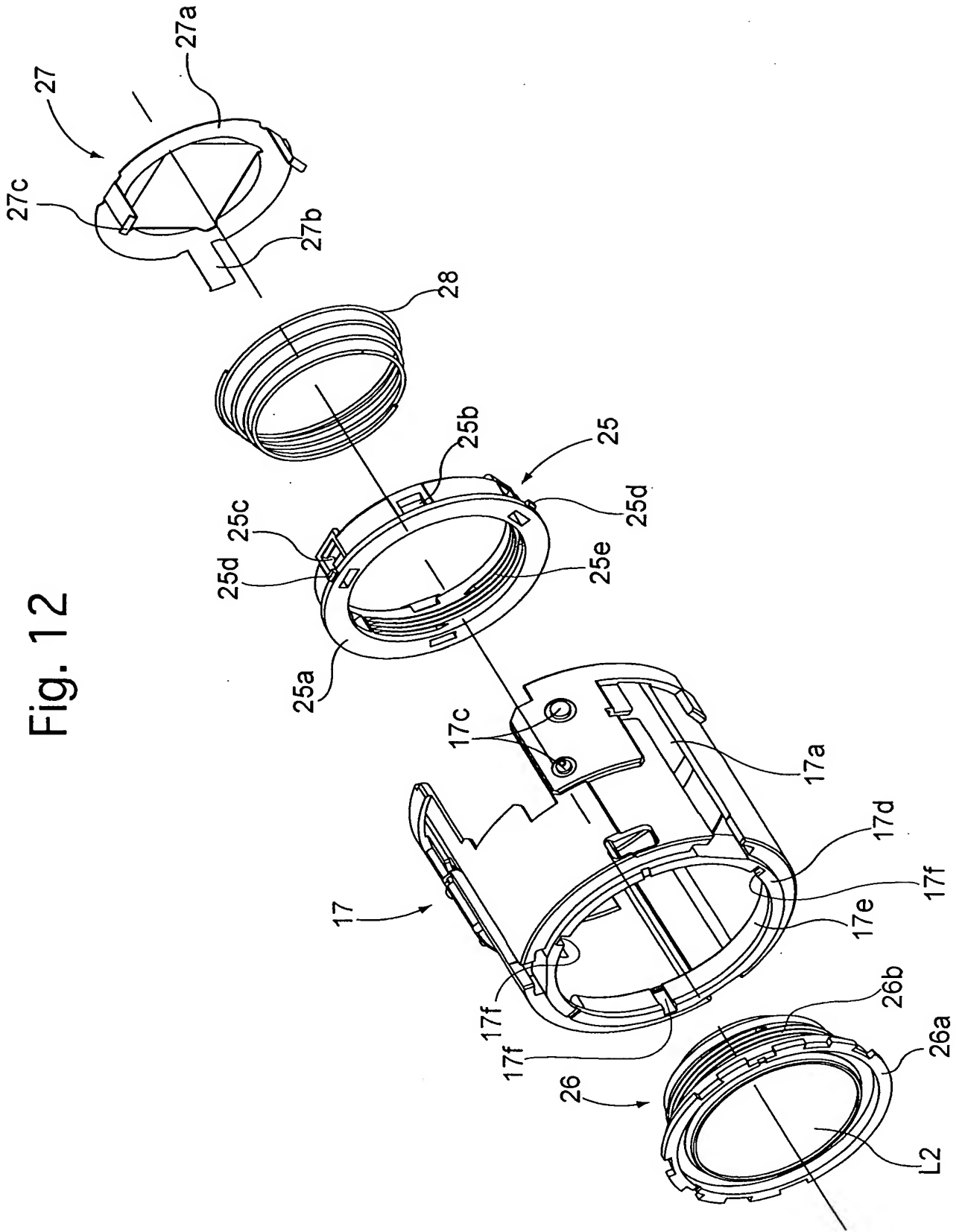


Fig. 14

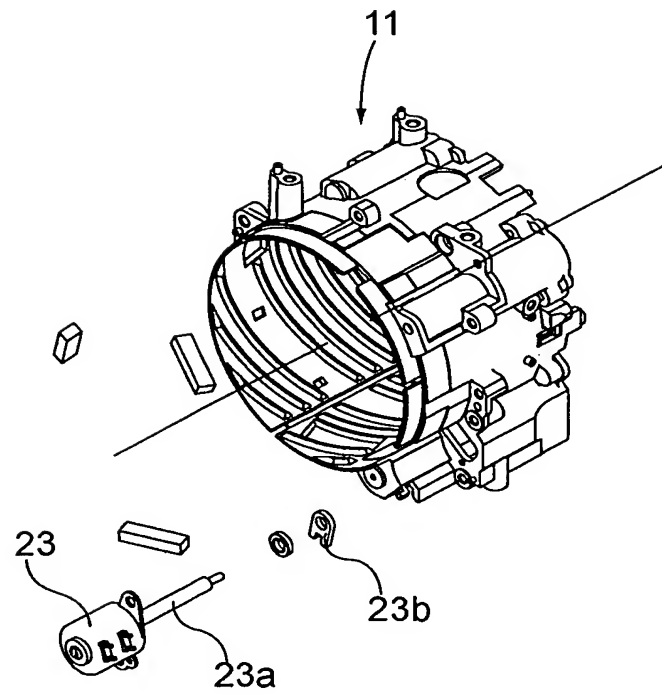


Fig. 15

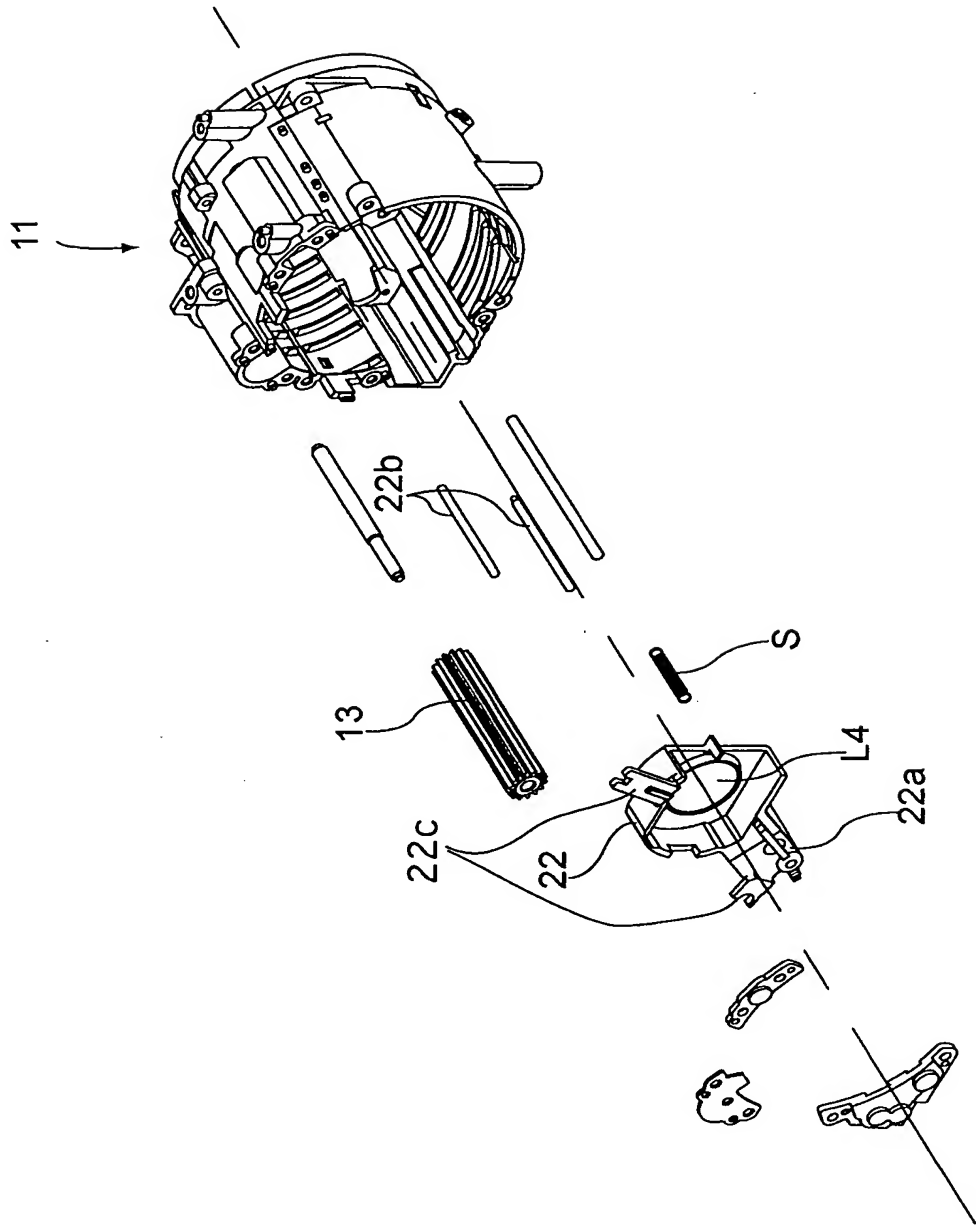


Fig. 16

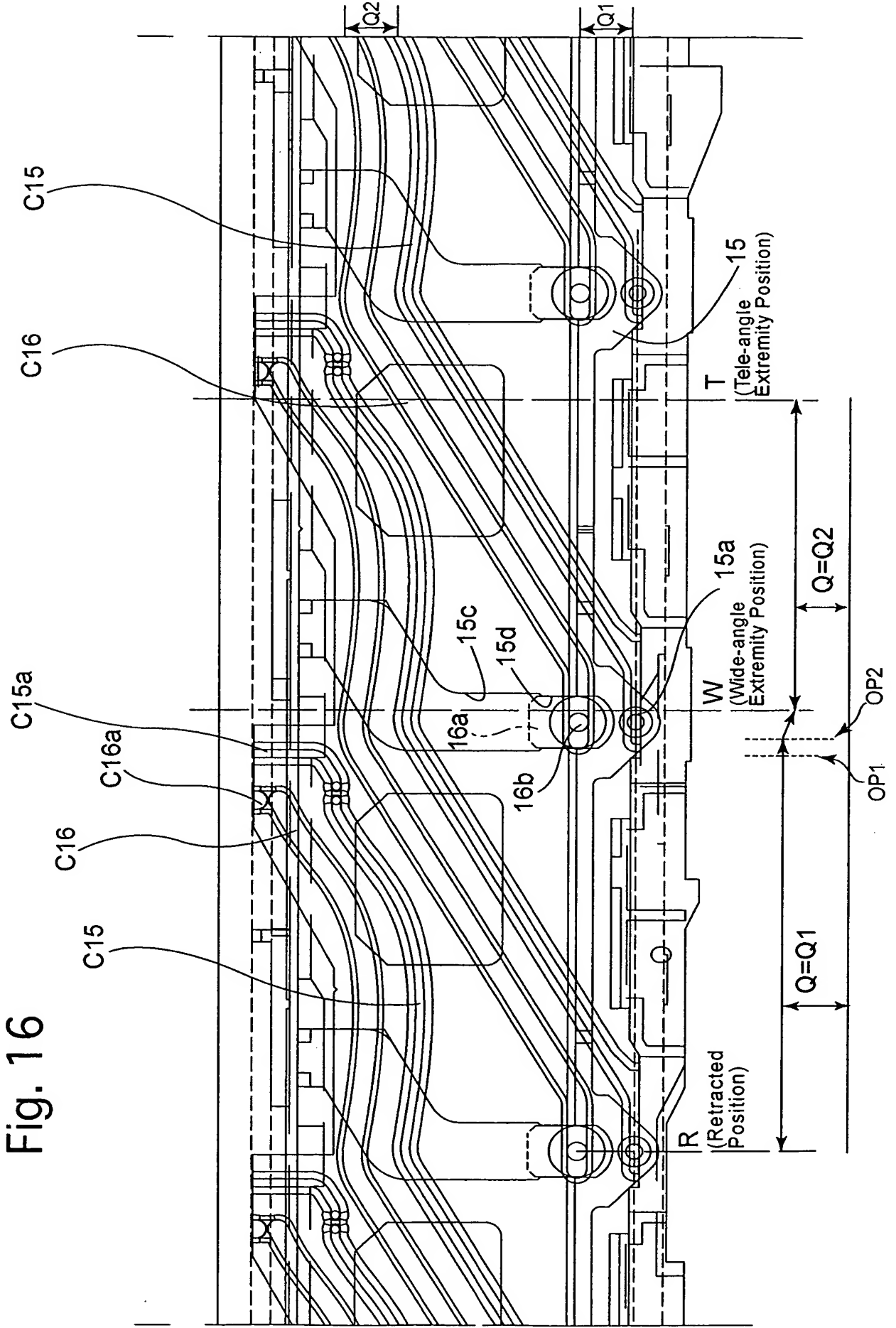


Fig. 17

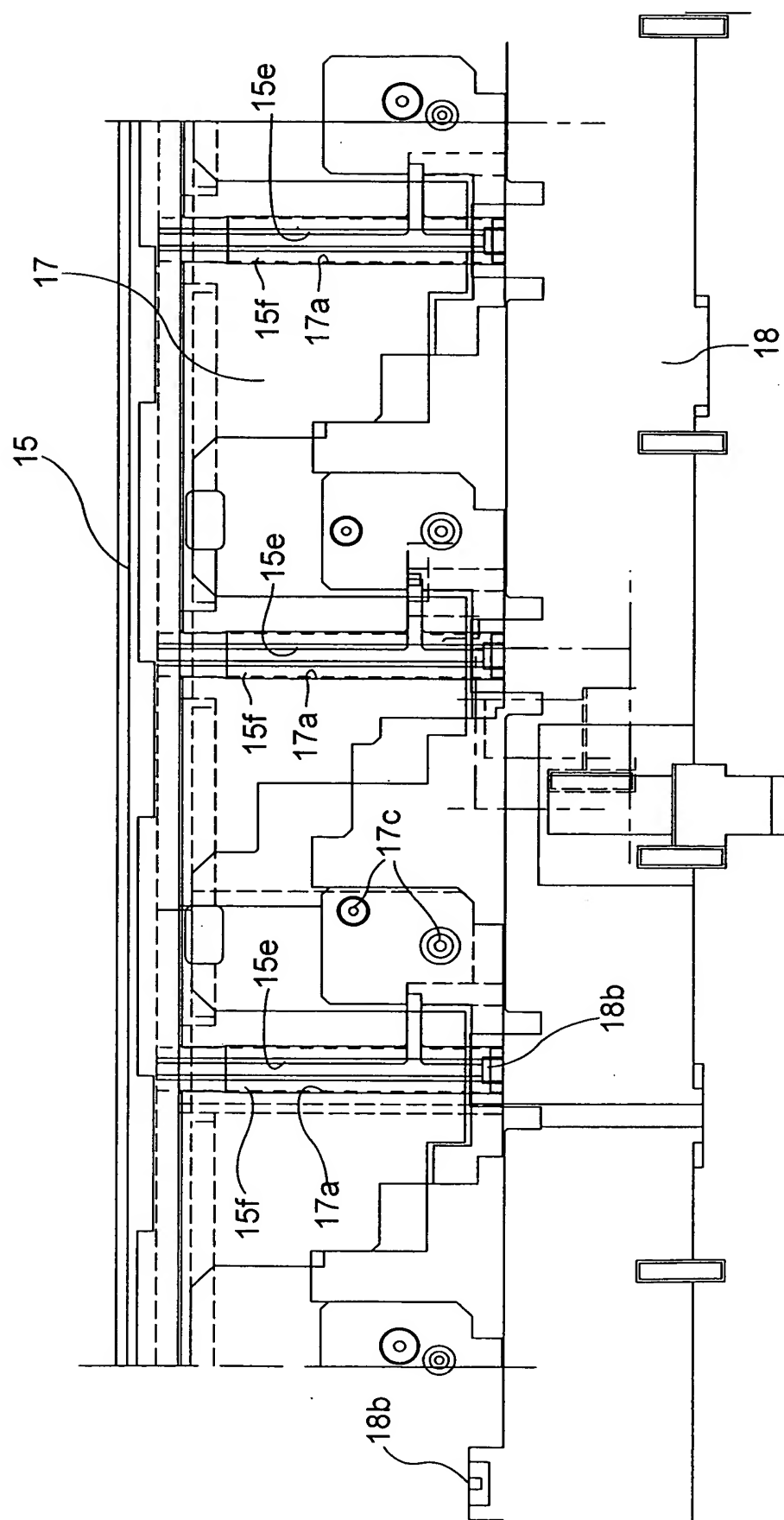


Fig. 18

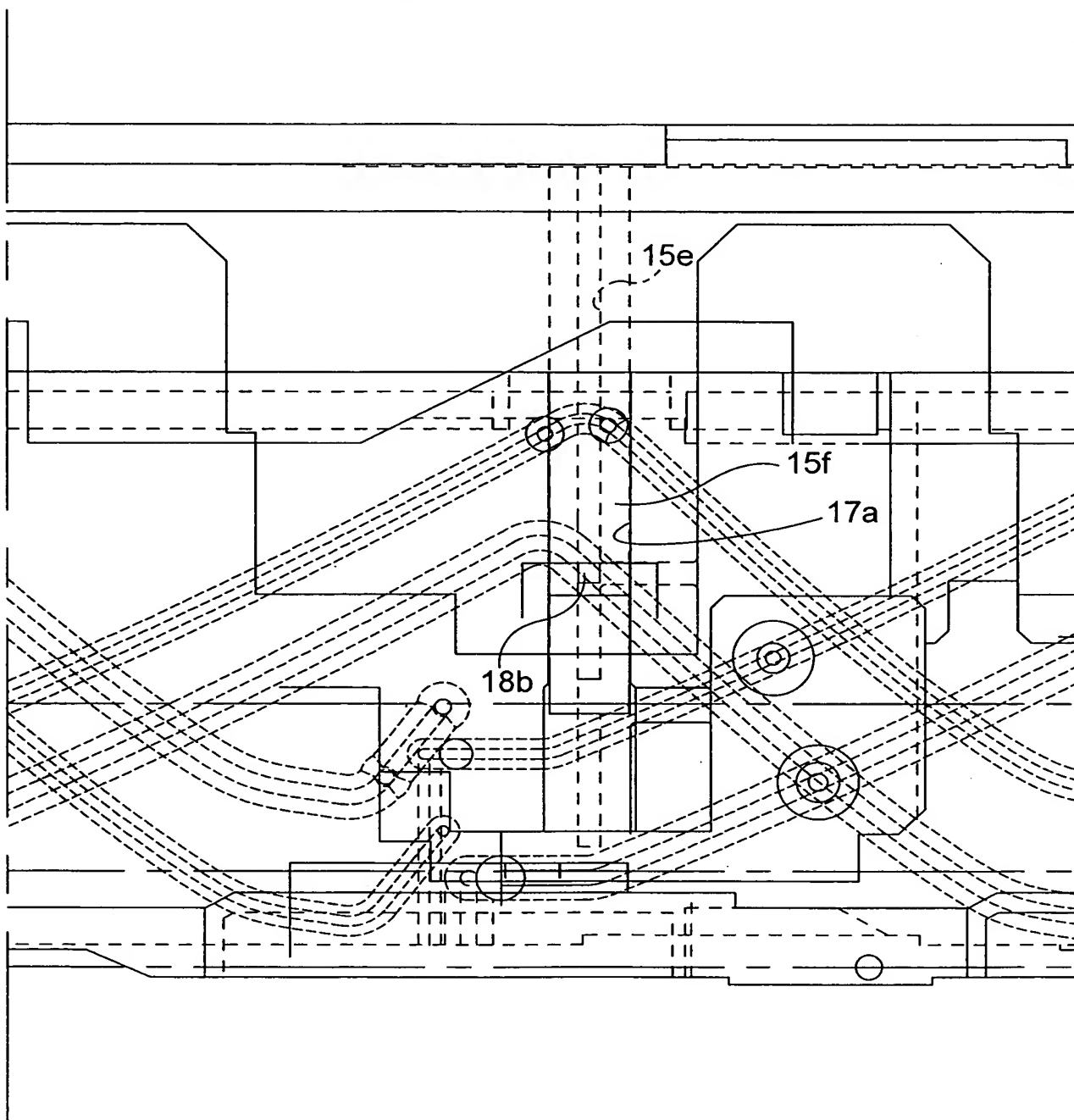


Fig. 19

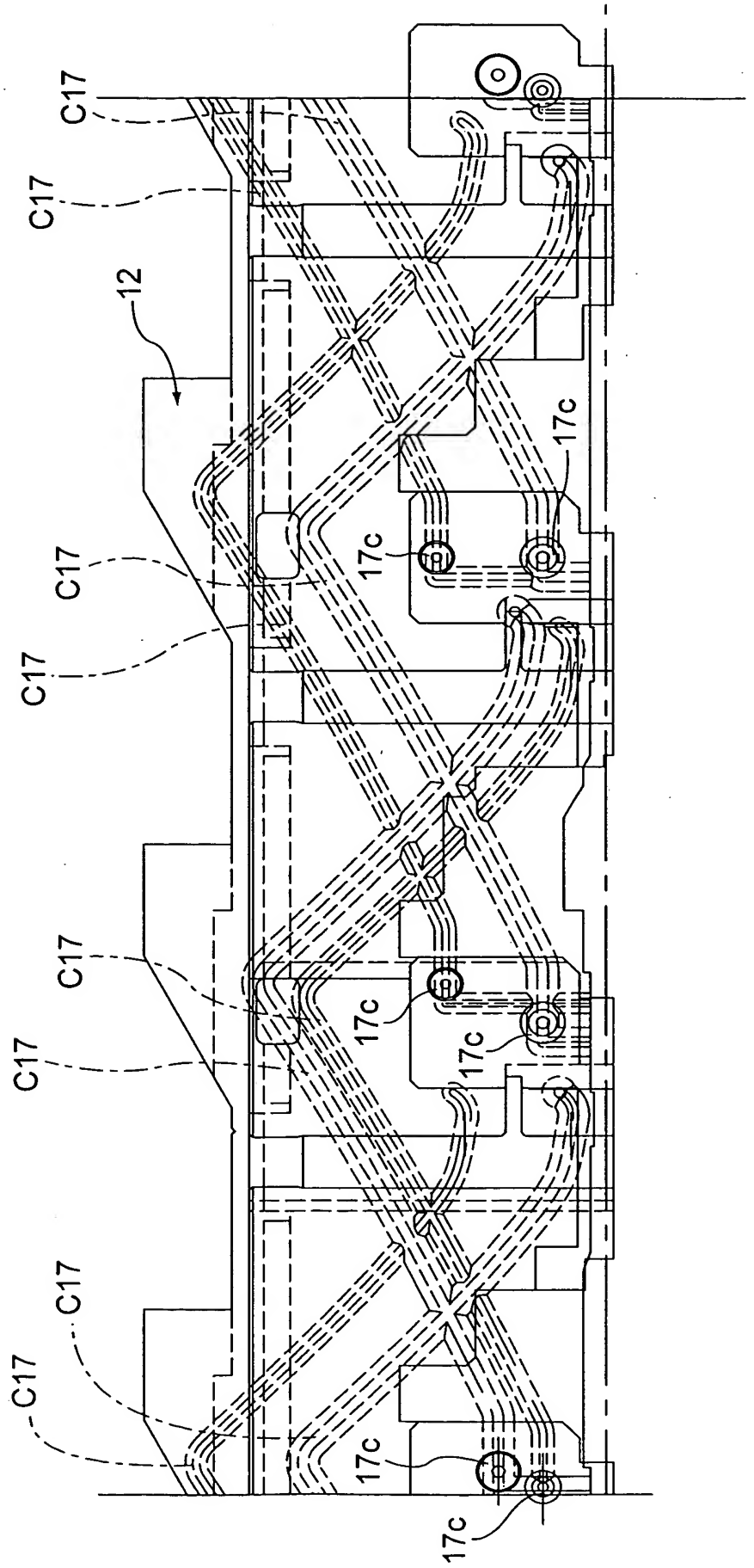


Fig. 20

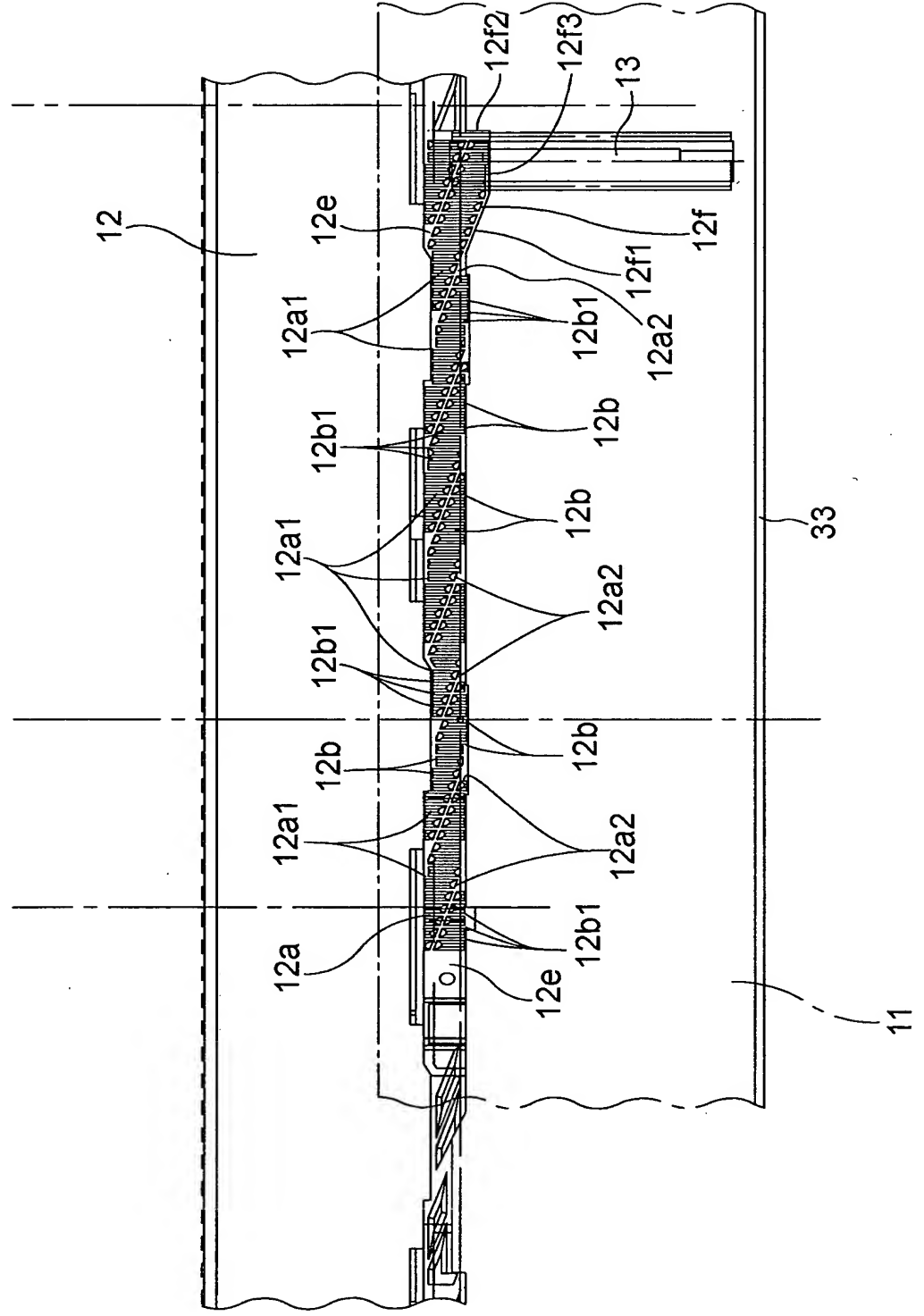


Fig. 21

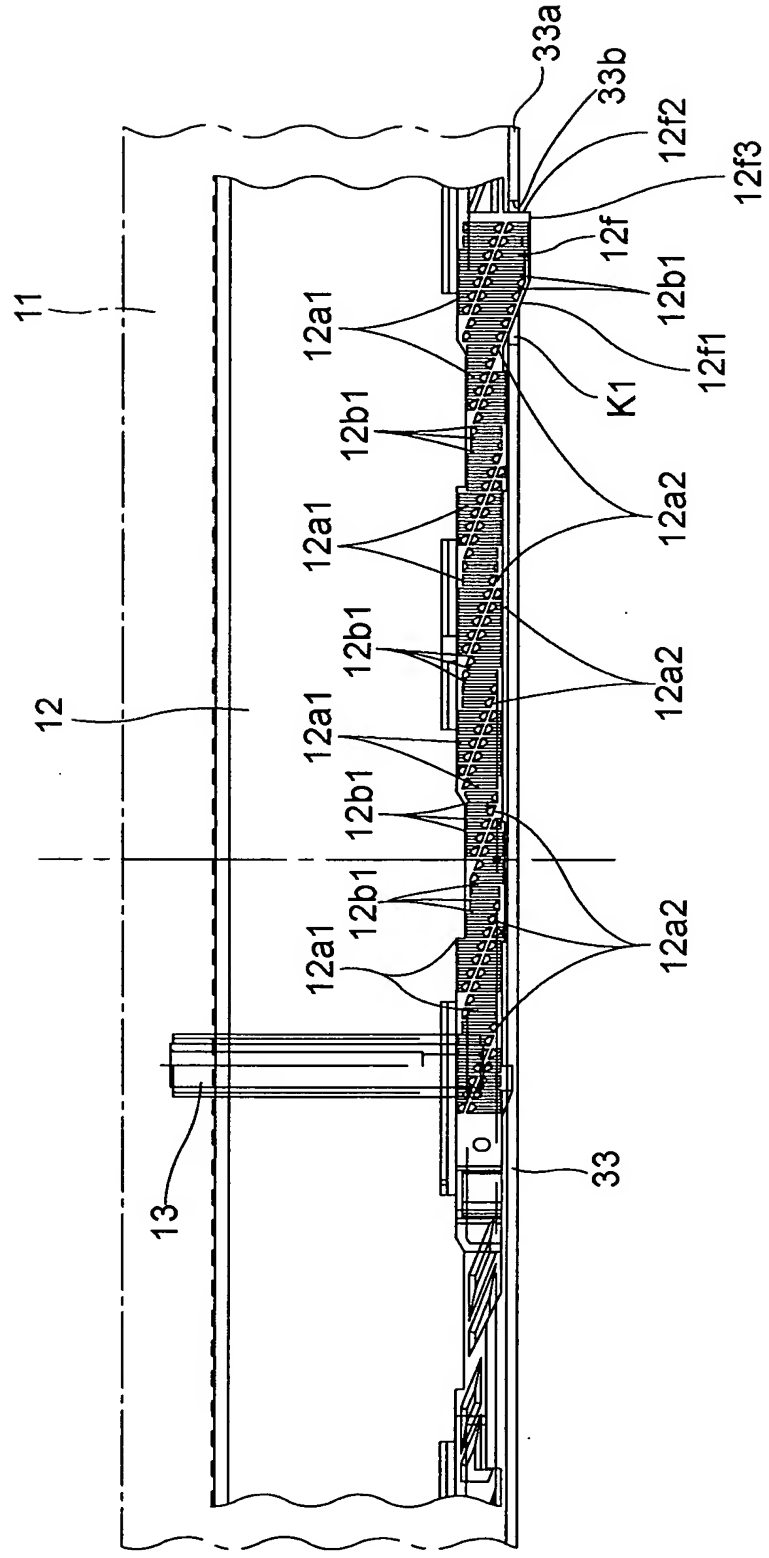


Fig. 22

